


Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 10/20/2016
TID #: TIDA-00756	Project Title: Low Power CO Gas Sensor w/ BLE Connectivity	
Number: TIDA-00756	Rev: E2	Sheet Title: Wireless MCU
SW/Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By: Gustavo Martinez	File: TIDA-00756_MCU_SchDoc	Size: B
Engineer: Gustavo Martinez	Contact: http://www.ti.com/support	





ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: <u>EVM orderable</u>	Designed for Public Release	Mod. Date: 10/20/2016	 TEXAS INSTRUMENTS
Part Number: <u>TIDA-00756</u>	Sheet Title: <u>Low Power CO Gas Sensor w/ BLE Connectivity</u>		
Number: <u>TIDA-00756</u> Rev: <u>E2</u>	Sheet Title: <u>Hardware</u>		
Source: <u>Version control disabled</u>	Assembly Variant: <u>No Variations</u>	Sheet 4 of 4	
Drawn By: <u>Version control disabled</u>	File: <u>TIDA-00756 Hardware_SchDoc</u>	Size: B	http://www.ti.com
Design: <u>Gustavo Martinez</u>	Contact: <u>http://www.ti.com/support</u>		© Texas Instruments 2016

A

B

C

D

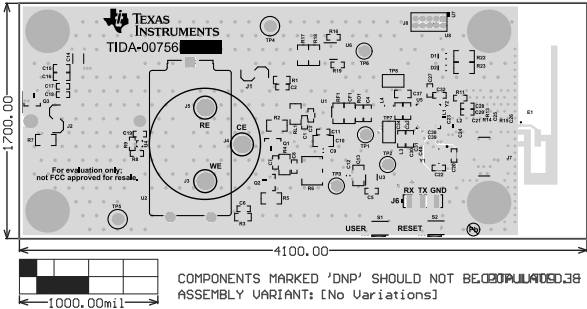
A

B

C

D

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



PCB NAME = TIDA-00756	BOARD # = 2100A-00756	DATE = 02/21/2016	DESIGNED BY = E2	SUN 3:28:16 PM 02/21/2016
LAYER NAME = TOP OVERLAY	TID #: 2100A-00756	# DIT		
PLATTNAME = TOP OVERLAY	Composited PCB	GENERATED BY: 10/21/2016 3:57:58 AM	DESIGNED BY: E2	TEXASINSTRUMENTS

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Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.42mil		
4	Dielectric 1	370HR	14.00mil	4.2	
5	Signal Layer 1	Copper	1.42mil		
6	Dielectric 2	370HR	10.00mil	4.2	
7	Signal Layer 2	Copper	1.42mil		
8	Dielectric 3	370HR	14.00mil	4.2	
9	Bottom Layer	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Impedance Control:

- Top layer contains 50 ohm impedance (+/- 10%) single ended using 24 mil lines (from E1 to U5)

DESIGN INFORMATION

MIN. TRACK WIDTH: 6_MIL
MIN. CLEARANCE: 6_MIL
MIN. VIA PAD SIZE: 20_MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5_MIL, HOLES +/- 3_MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3_MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER
THICKNESS: ☐ 62 MIL (1.6mm) +/-10% ☒ OTHER 44 MIL +/-10%
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL:
☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER



PROJECT TITLE:
Low Power CO Gas Sensor w/ BLE Connectivity

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00756.PcbDoc

ENGINEER:
Gustavo Martinez

LAYOUT BY:
Krypton Solutions/RS

SCALE: 0.72

ALTUM DESIGNER VERSION:
16.0.9.368

Comment	Description	Designator	Footprint	LibRef	Quantity
Printed Circuit Board	Printed Circuit Board	PCB1		P-CB	
BS-7	Battery Holder, CR0332 Returner: csp, TH	B01	BAT-BS-7	BS-7	1
C04H2J8NPNQWBN10	CAP, CERAM, 10 pf, 50 V, +/- 5%, COG/NPO, SMD	C1, C2, C3, CA, C7, C11	D402	C104H2J8NPNQWBN10	6
C1608KSR0110K080AC	CAP, CERAM, 10 pf, 16 V, +/- 10%, X5R, SMD	C4	D403	C1608KSR0110K080AC	1
C0403C102JBRACU	CAP, CERAM, 1000 pf, 3 V, +/- 5%, X7R, SMD	C5	D402	C0403C102JBRACU	1
C1005K7R1H104K	CAP, CERAM, 10 pf, 10 V, +/- 10%, X7R, SMD	C8	D402	C1005K7R1H104K	1
C0403C104KBRACU	CAP, CERAM, 10 pf, 10 V, +/- 10%, X7R, SMD	C9, C12	D403L	C0403C104KBRACU	2
C2012K5R010M	CAP, CERAM, 10 pf, 0.3 V, +/- 20%, X5R, SMD	C10, C13	D805, JHV	C2012K5R010M	2
C2124KSR1A107M104A C	CAP, CERAM, 10 pf, 0.3 V, +/- 20%, X5R, SMD	C14	D206, JHV	C2124KSR1A107M104A C	1
C1608KSR010M4	CAP, CERAM, 10 pf, 16 V, +/- 20%, X5R, SMD	C15	D403	C1608KSR010M4	1
C1608K7R1C105K	CAP, CERAM, 10 pf, 16 V, +/- 10%, X7R, SMD	C16	D403	C1608K7R1C105K	1
C1005K7R1H104K050B	CAP, CERAM, 10 pf, 10 V, +/- 10%, X7R, SMD	C17	D402	C1005K7R1H104K050B	1
C1005K7R1C103K050B	CAP, CERAM, 10 pf, 10 V, +/- 10%, X7R, SMD	C18	D402	C1005K7R1C103K050B	1
GRM155R71C103KA01D	CAP, CERAM, 100 pf, 10 V, +/- 10%, X7R, SMD	C19	D402	GRM155R71C103KA01D	1
GRM155SC1E120AA01D	CAP, CERAM, 12 pf, 20 V, +/- 5%, COG/NPO, SMD	C20, C22, C28, C29	D402	GRM155SC1E120AA01D	4
GRM155SC1H120AA01D	CAP, CERAM, 12 pf, 50 V, +/- 5%, COG/NPO, SMD	C21	D402S	GRM155SC1H120AA01D	1
GRM155SC1H1H2BA01 D	CAP, CERAM, 12 pf, 50 V, +/- 8.3%, COG/NPO, SMD	C23, C24	D402S	GRM155SC1H1H2BA01 D	2
Used in BOM report	CAP, CERAM, 1000 pf, 10 V, +/- 10%, X7R, SMD	C25, C26, C40	D402S	Capacitor	3
GRM155R01A105KE1SD	CAP, CERAM, 10 pf, 10 V, +/- 10%, X5R, SMD	C27	D402	GRM155R01A105KE1SD	1
Used in BOM report	CAP, CERAM, 1000 pf, 10 V, +/- 10%, X7R, SMD	C30	D403	Capacitor	1
GRM155R70104KA01D	CAP, CERAM, 10 pf, 0.3 V, +/- 10%, X7R, SMD	C31, C38, C39	D402S	GRM155R70104KA01D	3
GRM155R70104KA01D	CAP, CERAM, 10 pf, 0.3 V, +/- 10%, X7R, SMD	C32	D402	GRM155R70104KA01D	1
GRM188R0104ME4TD	CAP, CERAM, 10 pf, 0.3 V, +/- 20%, X5R, SMD	C33, C37	D403	GRM188R0104ME4TD	2
GRM188R71C104KA01D	CAP, CERAM, 10 pf, 20 V, +/- 10%, X7R, SMD	C34	D403	GRM188R71C104KA01D	1
C1005K7R1H1222K	CAP, CERAM, 2200 pf, 50 V, +/- 10%, X7R, SMD	C35, C36	D402	C1005K7R1H1222K	2
08053C104KA72A	CAP, CERAM, 10 pf, 25 V, +/- 10%, X7R, SMD	C31	D805, JHV	08053C104KA72A	1
LS129K-G12-1-2	LED, Blue, SMD	D1	LS129K_Std	LS129K-G12-1-2	1
LY29K-4HX2-26-2	LED, Yellow, SMD	D2	LY29K_Std	LY29K-4HX2-26-2	1
ANTENNA_DN007A	2.4GHz PCB Antenna to be soldering to bag or mount.	D3	ANTENNA_DN007A	ANTENNA_DN007A	1
Fiducial	Fiducial mark. There is nothing to be bag or mount.	FID1, FID2, FID3, FID4, FID5, FID6	Fiducial16-20	Fiducial	6
NYPMS 440 0025 PH	Machine Screw, Round #4-40 x 1/4, Nylon Phillips panhead	H1, H2, H3, H4	NYPMS 440 0025 PH	NYPMS 440 0025 PH	4
V820C	Micro: 2.54mm, 2x8, Gold, BGA, SMT	H5, H6, H7, H8	Kyotona, V820C	V820C	4
8798F-0304	Micro: 2.54mm, 2x8, Gold, BGA, SMT	J1, J2	Molux, 8798F-0304	8798F-0304	2
3-50871-2	CONN, SOCKET, RCPT 08-08 3040, Gold, TH	J3, J4, J5	TE, 3-50871-2	3-50871-2	3
S-144280-3	Module: 2.54mm, 8x4, Gold, TH	K6	TE, S-144280-3	S-144280-3	1
CON3MA001-SMD-G	Conn: 2.54mm, 8x4, SMT	L1	TE, CON3MA001-SMD- G	CON3MA001-SMD-G	1
GRW05Z0WVN-BC	Inductor: 50mH, 5x4, Gold, TH	L8	CON, GRW05Z0WVN- BC	GRW05Z0WVN-BC	1
LOG15H515N02D	Inductor: Multilayer, Air Core, 15 mH, 0.3 A, 0.30 ohm, SMD	L1	IND, LOG15H	LOG15H515N02D	1
LOG15H52N050D	Inductor: Multilayer, Air Core, 2 mH, 0.3 A, 0.1 ohm, SMD	L2	IND, LOG15H	LOG15H52N050D	1
BLM18HE1525N1D	Ferrite Bead, 1500 ohm @ 100 MHz, 0.5 A, 0.625 ohm, SMD	L3	D403	BLM18HE1525N1D	1
CX5212510MM-T	Inductor: Multilayer, Ferrite, 10uH, 0.11A, 0.62 ohm, SMD	L4	D805, L45	CX5212510MM-T	1
MMMF 270	10k 1/4W, 20 V, 0.05% A, 501-23	C1, C2	501-23	MMMF 270	2
9232305	RES, 0.1%, 0.1 W, 5000 A, 501-23	C13, C14	501-23	9232305	1
CRW080520M020EA	RES, 0.1%, 0.1 W, 5000 A, 501-23	R1, R3	D403	CRW080520M020EA	2
CRW080520M020EA	RES, 2.0 M, 5%, 0.125 W, 0.605	R2	D805, JHV	CRW080520M020EA	1
BR-AGEW234V	RES, 2.2 M, 10%, 0.125 W, 0.605	R4	D805, JHV	BR-AGEW234V	1
CRW080520M5FKEA	RES, 2.2 M, 1%, 0.125 W, 0.605	R5	D805, JHV	CRW080520M5FKEA	1
3224W-1-205E	RES, 0.5%, 0.125 W, 0.25W SMD	R6	TRIM, 3224W	3224W-1-205E	1
CRW0805000020EA	RES, 0.5%, 0.125 W, 0.25W SMD	R7, R10, R12, R13	D805, JHV	CRW0805000020EA	4
CRW040424K75FKE0	RES, 4.75 K, 1%, 0.063 W, 0.402	R8, R9	D402	CRW040424K75FKE0	2
CRW04042000020ED	RES, 0.5%, 0.063 W, 0.402	R11, R16	D402	CRW04042000020ED	2
CRW04042000020ED	RES, 0.5%, 0.063 W, 0.402	R12, R14, R15	D402S	CRW04042000020ED	3
BR-AGEW1492V	RES, 14.9 K, 1%, 0.125 W, 0.605	R17	D805, JHV	BR-AGEW1492V	1
BR-AGEW1943V	RES, 19.4 K, 1%, 0.125 W, 0.605	R18	D805, JHV	BR-AGEW1943V	1
CRW04042100FKE0D	RES, 10.0 K, 1%, 0.063 W, 0.402	R19	D402	CRW04042100FKE0D	1
CRW04042475FKE0D	RES, 47.5 K, 1%, 0.063 W, 0.402	R20, R21	D402	CRW04042475FKE0D	2
CRW08054428FKEA	RES, 44.2 K, 1%, 0.125 W, 0.605	R22	D805, JHV	CRW08054428FKEA	1
CRW08054878FKEA	RES, 487.1 K, 0.125 W, 0.605	R23	D805, JHV	CRW08054878FKEA	1
CRW08051678FKEA	RES, 1.78 M, 1%, 0.125 W, 0.605	R24	D805, JHV	CRW08051678FKEA	1
CRW040424K9FKEA	RES, 49.9 K, 1%, 0.1 W, 0.402	R25	D403	CRW040424K9FKEA	1
B3U-1000P	SWITCH, TACTILE, SPST- NO, 0.05A, 12V	S1, S2	SW, B3U-1000P	B3U-1000P	2
REY102-0080-DA	Shunt, 100m, Gold plated, Black	SH-J1, SH-J2	SH-J1-BK-G	REY102-0080-DA	2
0084	Test Point, Miniature, Yellow, TH	TP1, TP2, TP3, TP6	Kyotona0084	0084	4
S011	Test Point, Multipurpose, Black, TH	TP4, TP5	KyotonaS011	S011	2
S015	Test Point, Miniature, SMT	TP7, TP8	Testpoint1,Kyotona,JA nature	S015	2
LPV8110BWR	Precision 820 DA Noninverting Operational Amplifier, CMR0005A (201-0)	U1	DRV0050A, N	LPV8110BWR	1
T055342	Carbon, Miniature Detector, TH	U2	FIASCO, T055342	T055342	1
TLV3691DC08	0.9-V to 4.5-V, Nonprecision Comparator, DC0005A	U3	DC0005A, N	TLV3691DC08	1
TMP105A9FFB	1-Wire, 1-Wire Temperature Sensor with Two-Wire Interface in WSP, BT500A9AAA	U4	BT500A9AAA	TMP105A9FFB	1
CC2A05F128BSMR	Ultra low-power ARM Cortex-M0+ 2.4 GHz Radio MCU, RS000328	U5	RS000328	CC2A05F128BSMR	1
TR15111DDCB	Waveform Generator Timer for Power Gating DC000AA	U6	DC000AA, N	TR15111DDCB	1
TE1110B04QPW	1SD in Q402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2-pin, 2500A (DIP), Green (RoHS & not Pb-free)	U7, U8, U9, U10	DPW002A	TE1110B04QPW	4
100-3225	CP2001-24 MHz, 7-pin			100-3225	
24-0000MF-20C-AC3	SMD			EPSON, T04-3225	24-0000MF-20C-AC3
TC-12M-32-7680A-A3	Crystal, 32.768MHz, 12.5			Epson, TC-12M	TC-12M-32-7680A-A3